Abstract:

Method for polishing a substrate composed of semiconductor material

The invention relates to a method for polishing a substrate composed of semiconductor material, comprising at least one polishing step of type A, by means of which the substrate is polished on a polishing pad containing an abrasive material bonded in the polishing pad, wherein a polishing agent solution is introduced between the substrate and the polishing pad during the polishing step; and at least one polishing step of type B, by means of which the substrate is polished on a polishing pad containing an abrasive material bonded in the polishing pad, wherein a polishing agent slurry containing unbonded abrasive material introduced between the substrate and the polishing pad during the polishing step.

(No Fig)